

1. Record Nr.	UNISA996279447203316
Titolo	2015 International 3D Systems Integration Conference (3DIC 2015) : Sendai, Japan, 31 August - 2 September 2015 // Institute of Electrical and Electronics Engineers
Pubbl/distr/stampa	Piscataway, NJ : , : IEEE, , [2015] ©2015
ISBN	1-4673-9385-1 1-4673-9386-X
Descrizione fisica	1 online resource (353 pages) : illustrations
Disciplina	621
Soggetti	Three-dimensional integrated circuits
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Includes index.
Sommario/riassunto	Annotation The IEEE 3DIC 2015 will cover all 3D integration topics, including 3D process technology, materials, equipment, circuits technology, design methodology and applications.